

Vintage: June. 2009

Wafer Size: 300mm

SW Version: 5.1.0

Main Process: Photo

Sub-Process: ARF-Scanner

(2) Hardware Configuration:

	Moudule	Check Items	Yes or No	Remarks
1	OIU	Is the motherboard complete?	✓	
2		Are the keyboard, mouse, and monitor working properly?	✓	
3	WH	Hardware defects or damage	X	The motherboard has been taken apart. The engineer said it was previously disassembled
4		Are there any scratches or dirt on the component gripper or TSU surface?	X	
5	WS	Hardware defects or damage	✓	The tsmc engineer said all the machines can be initialized except WS, which has a small
6		Are there any scratches or dirt on the surface of the component Closing Disk?	X	Adsorb on the lens bottom.
7		Are there any scratches or dirt on the surface of the mirror block components?	✓	A little bit of particle water stain
8		Are there any scratches or dirt on the Z-mirror component surface?	✓	A little bit of particle water stain
9		Are there any scratches or dirt on the surface of the image sensor components?	✓	A little particle
10		Are there any scratches or dirt on the surface of the wafer table component?	X	A little particle
11	RH	Hardware defects or damage	✓	T-bar missing
12	RS	Hardware defects or damage	X	
13		Are there any scratches or dirt on the R-chuck component surface?	X	
14	ILL	Hardware defects or damage	X	
15		Does the surface of the REMA lens have any scratches or dirt?	X	
16		Is there a number of Bending Points?	X	
17	Lens	Hardware defects or damage	X	
18		Are there any scratches or dirt on the top and bottom of the lens?	✓	A little particle
19		Is the sensor on the top of the lens complete?	✓	

	Moudule	Check Items	Yes or No	Remarks
20	EIM	Hardware defects or damage?	X	0.641
21		Hardware defects or damage?	X	
22	LMA&AOM	Hardware defects or damage?	X	
23	ELEC	Hardware defects or damage?	X	
24	WSRC	Hardware defects or damage?	X	
25	RSRC	Hardware defects or damage?	X	
26	ACC	Hardware defects or damage?	X	
27	LCWC	Hardware defects or damage?	X	
28	MCWC	Hardware defects or damage?	X	
29	WICC	Hardware defects or damage?	X	
30	WISC	Hardware defects or damage?	X	
31	Laser	Hardware defects or damage?	X	MODEL: Cymer XLA360

(3) Status of System: System safely powered down

SECS Control:
SECS Comm.:

Date: 2026/6/28
Time:

Screen Control:

Enable

Disable

RMCS

RMCS

User: ASML
Level: SERVICE ENG.

Status: Start Up Drivers

Imaging

Imaging Scan Control: Terminated

Illumination: Terminated

Projection: Terminated

Dose Control: Terminated

Rema Control: Terminated

Pressure Temperature Control: Terminated

Wet Imaging Control: Terminated

Metrology

Height & Tilt Control (E): Terminated

Coord. System Control-wafer: Terminated

Image Quality Control: Terminated

Height & Tilt Control (M): Terminated

Coord. System Control-blue: Terminated

Metrology Driver: Terminated

Production Control

Expose Control: Terminated

Expose Scan Control: Terminated

Swap Control: Terminated

Measure Control: Terminated

Route Control: Terminated

Maintenance Scheduler: Terminated

Start Up

Drivers

Maintenance

Drivers

Wafer Alignment & Levelling

Level Scan Control: Terminated

Level Sensor: Terminated

Alignment Scan Control: Terminated

Alignment Subsystem: Terminated

Mark Type Database: Terminated

Image Alignment & Quality

Image Sensor Scan Control: Terminated

Image Sensor sub-system: Terminated

ILIAS Scan Control: Terminated

ILIAS sub-system: Terminated

Polarization Scan Control: Terminated

Support

Synchronisation (M): Terminated

Synchronisation (E): Terminated

M.System Interferometers: Terminated

Flow & Temperature Control: Terminated

Air Mounts: Terminated

Water Table Cleaning: Terminated

Shut Down

Drivers

System

System and UNIX

Refresh

Driver Status

Wafer Flow

Stages Scan Control: Terminated

Wafer Stage: Terminated

Water Handler: Terminated

Wafer Logistics: Terminated

Reticle Flow

Reticle Stage: Terminated

Reticle Handler: Terminated

Reticle Logistics: Terminated

Start Up Drivers: Terminated

Task/Host Monitor

Initialized

Busy

Terminated

Failed

M=Measure
E=Expose

0%

(4) System Acceptance Test:

TWINSKAN XT:1700Fi SYSTEM ACCEPTANCE TESTS

Model: XT1700Fi			
Category	Items	Spec	Result-Data
Full Acceptance Test		XT1700Fi	Result-Data
1. Overlay	1.1 Single machine overlay	≤ 5	NA
2. Intensity	2.1 Slit integrated power, 11 scans in 26mm Setting 1 [mW/cm]	$\geq 1650^{**}$	NA
3. Projection Lens	3.1 RMS Z5-Z37 [nm]	≤ 1.4	1.36
	3.2 RMS Spherical [nm]	≤ 0.8	0.67
	3.3 RMS coma [nm]	≤ 0.8	0.4
	3.4 RMS astigmatism [nm]	≤ 0.8	0.5
	3.5 RMS 3-foil [nm]	≤ 0.8	0.7
	3.6 Long range straylight [SAMOS %]	≤ 0.9	NA
	3.7 Short range straylight [SAMOS %]	≤ 1.2	NA
4. Illumination	4.1 Dose system performance, setting 1 [%]	≤ 1.0	NA
	4.2 Integrated slit uniformity, setting 1 [%]	≤ 0.30	NA
	4.3 Integrated scan uniformity, setting 1 [%]	≤ 0.2	NA
	4.4 Dose repeatability [%]	≤ 0.2	NA
	4.5 Dose accuracy setting 1 [%]	± 0.7	NA
5. Pupil Verification	5.1 Ellipticity, Setting 1 [meam]	≤ 1.5	NA
	5.2 Sigma variation setting 1 [range]	≤ 0.007	NA
6. Focus and Leveling	6.1 Wafer map repeatability (99.7%) [nm]	≤ 8	NA
7. Dynamic Performance	7.1 MA X&Y (mean+3ig) [nm]	≤ 2.0	NA
	7.2 MSD X&Y (max of mean per field) [nm]	≤ 6.5	NA
	7.3 Inspection time (<200 particles found) [nm]	≤ 225	NA
	7.4 Size accuracy - lates spheres () Upper surface		
	10um [um]	± 3	NA
	30um [um]	± 3	NA
	50um [um]	± 5	NA
	7.5 Size accuracy - latex spheres () Lower surface		
	10um [um]	± 3	NA
	30um [um]	± 3	NA
	50um [um]	± 5	NA
8. BMWL - fine	Test results		NA
9. TSPE	Test results		NA
10. SWZS	Test results		NA